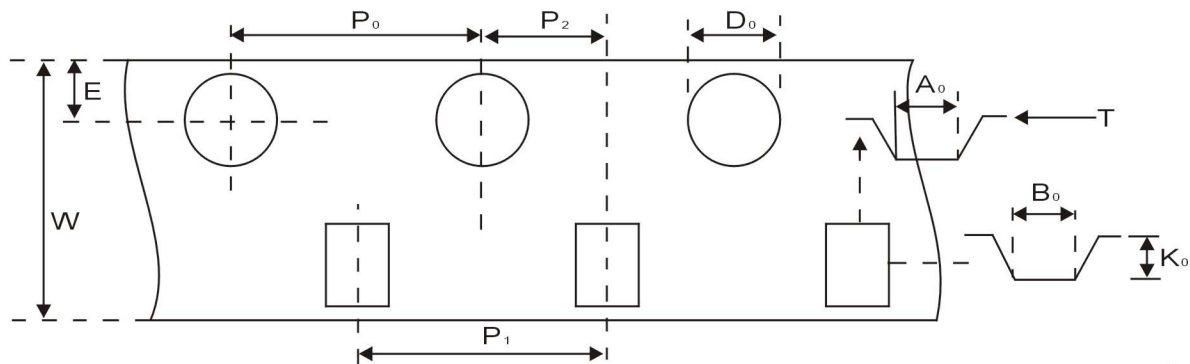


MULTILAYER CERAMIC CHIP CAPACITOR(MLCC)



Dimensions of Embossed Packing(plastic tape)



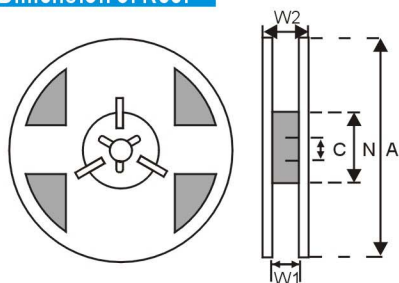
Unit:mm

Mark	Chip size	0201	0402	0603	0805	1206	1808	1812	2225	3035
A ₀ (width of compartment)		0.3±0.1	0.63±0.1	1.0±0.15	1.5±0.2	1.85±0.2	2.3±0.2	3.4±0.2	6.7±0.3	9±0.3
B ₀ (length of compartment)		0.55±0.1	1.13±0.1	1.8±0.15	2.3±0.2	3.5±0.2	4.8±0.2	4.8±0.2	6.0±0.3	8±0.3
K ₀ (depth of compartment)		0.6±0.3	1.0±0.3	1.0±0.3	1.4±0.3	X 1.5±0.2	X 1.4±0.2	X 1.4±0.2	F 1.7±0.2	F 1.7±0.2
						F 1.7±0.2	F 1.7±0.2	F 1.7±0.2	Z 2.2±0.2	Z 2.2±0.2
						L 2.3±0.2	Z 2.2±0.2	Z 2.2±0.2	Z 2.2±0.2	E 2.7±0.2
							E 2.7±0.2	E 2.7±0.2	E 2.7±0.2	A 3.2±0.3
D ₀ (diameter of sprocket hole)		1.55±0.1	1.55±0.1	1.55±0.1	1.55±0.1	1.55±0.1	1.55±0.1	1.55±0.1	1.55±0.2	1.55±0.2
W (tape width)		8.0±0.2	8.0±0.2	8.0±0.2	8.0±0.2	8.0±0.2	12.0±0.2	12.0±0.2	12.0±0.2	12.0±0.2
P ₁ (compartment pitch)		2.0±0.1	2.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	8.0±0.1	8.0±0.1	8.0±0.1
P ₂ (distance between centers of compartment hole and chip hole)		1.0±0.1	1.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1	2.0±0.1
E (distance between a sprocket hole and upper)		1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1
T (tape thickness)		0.25±0.1	0.25±0.1	0.25±0.1	0.25±0.1	0.25±0.1	0.25±0.1	0.25±0.1	0.25±0.1	0.25±0.1
H (Sprocket hole pitch)		2.0±0.1	2.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1

Emboss tape: for thickness code X,F,L,Z,E

Dimension of Reel

Unit:mm



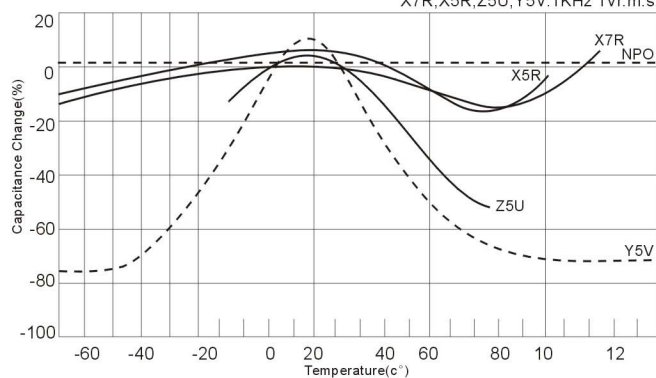
Reel size	A	N	C	W1	W2(max.)
7"	179±2	60±2	13.0±0.5	9.4±1.0	14.4
7"	179±2	60±2	13.0±0.5	12.0±0.5*	16.0
10"	254±2	100±2	13.0±0.5	9.5±1.0	14.4
13"	330±2	100±2	13.0±0.5	9.5±1.0	14.4

*Plastic Tape

Reference data

CAPACITANCE-TEMPERATURE CHARACTERISTICS

Measuring Condition NPO :1MHz, 1Vr. m. s.
X7R,X5R,Z5U,Y5V:1KHz 1Vr.m.s.



CAPACITANCE-TEMPERATURE CHARACTERISTICS

